

Preliminary Results of Tests on TRD Front End Prototype Chip

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INTRODUCTORY REMARKS

- The main purpose of my presentation is to show results of the preliminary tests on a HCR-TRD front end prototype chip.
- ASIC test needs an appropriate infrastructure.

It was designed, built and tested:

- PCB – as chip mounting/bonding base
- Test Board – for electronic tests of the chip
- Mother Board – for testing the chip as HCR-TRD FEE

TB and MB contain the following blocks:

- power supplies
- adjustable voltage references
- digital (logic) interface (between chip and DAQ)
- analog interface (buffers)

HCR-TRD ASIC Test Board

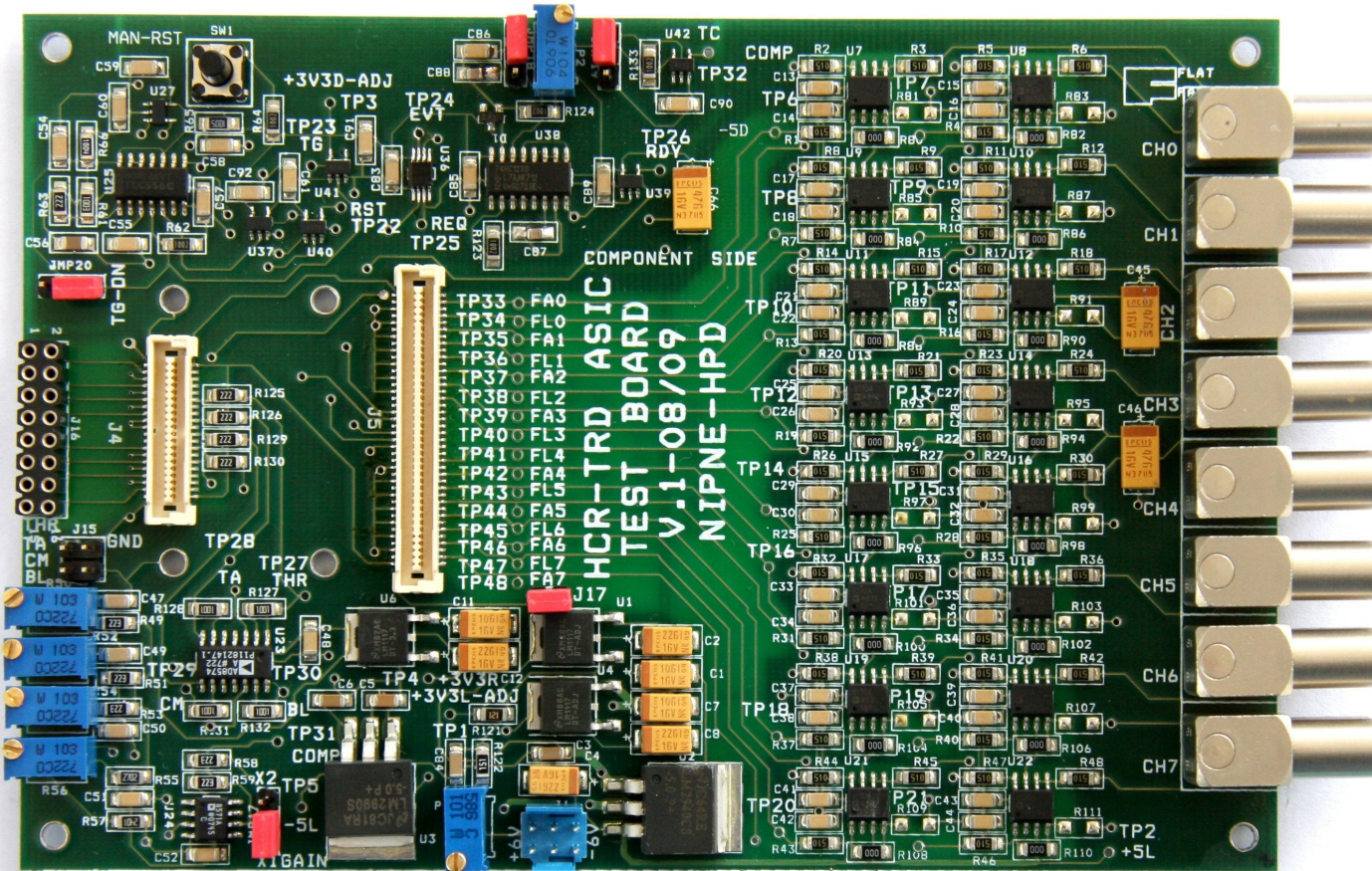


FIG. 3

TEST CONDITIONS

Unless otherwise specified:

- Setup:

- Pulse Generator HP8004A ($T_R \approx 0.8$ ns)
- Digital Oscilloscope DPO 4104 (BW = 1GHz, SR = 5 GS/s)
- Digital Multimeter HP 34401A (6 digits)
- NIM Standard Power Supply (+/- 6VDC)

- Chip settings:

- power supply = 3.3 V
- baseline level = 500 mV
- common reference = 1 V
- threshold level = 100 mV
- shaping time = 40 ns

DC TESTS

→ Variation of quiescent supply current vs. operating voltage:

Operating voltage	3.0	3.3	3.6	V
Quiescent current	29.68	30.32	30.71	mA

$\Delta I \approx 1 \text{ mA}$

Predicted power consumption:
11mW/(analog ch.)

Measured:

12.5 mV/(analog ch. + logic circuitry)

→ Baseline level adjustment: 0.2 → 1.0 V (design specification)

→ Variation of baseline vs. leakage current injected at the input of the chip:

Ch. no.	Leakage current			Δ	
	- 50 nA	0	+ 50 nA		
0	492.0	492.49	492.87	0.87	mV
7	494.38	494.7	494.89	0.51	mV

Fast out

Design specification:
0.50 mV

Ch. no.	Leakage current			Δ	
	- 50 nA	0	+ 50 nA		
0	497.8	498.34	498.65	0.85	mV
7	493.92	494.33	494.46	0.54	mV

Peak sense out

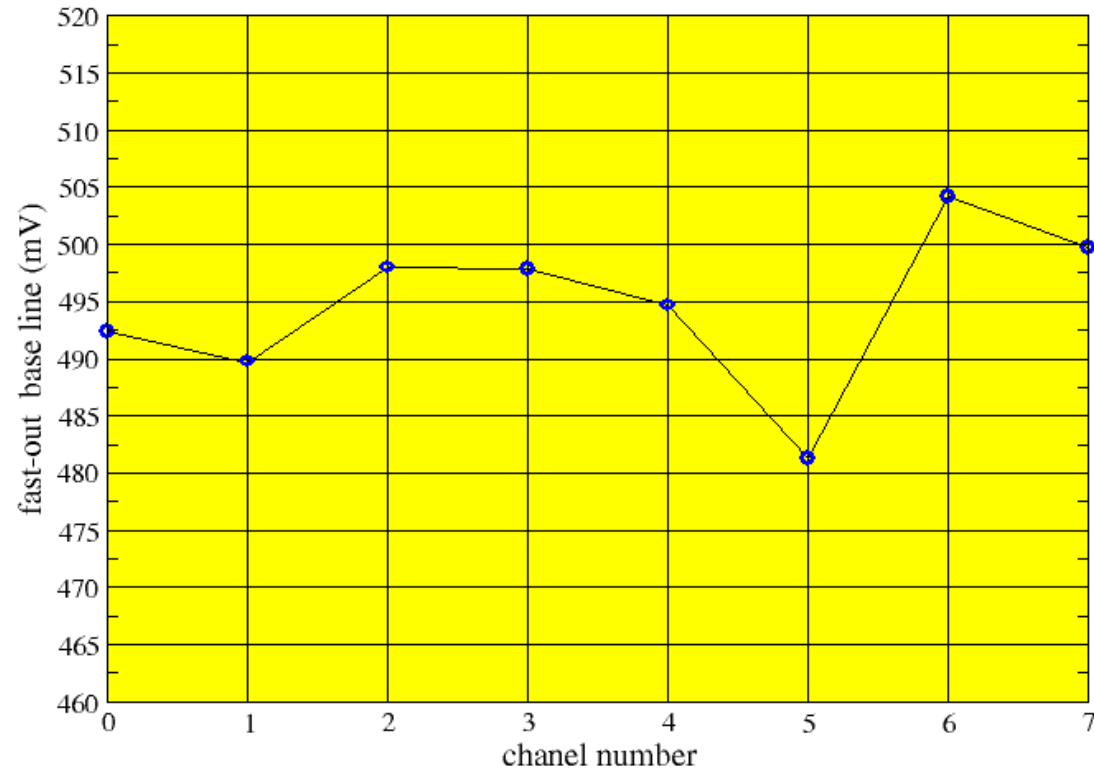
→ Variation of baseline vs. channel no. and vs. power supply:

Ch. no.	Power supply			Δ	
	3.0 V	3.3 V	3.6 V		
0	492.74	492.37	492.36	0.38	mV
1	489.93	489.70	189.67	0.26	
2	498.23	497.93	497.88	0.35	
3	498.17	497.87	497.75	0.42	
4	499.93	499.68	499.65	0.28	
5	504.55	504.20	504.19	0.36	
6	481.45	481.27	481.29	0.16	
7	494.86	494.62	494.51	0.35	

Fast out

Predicted: 0.35mV

Chip fast-out base line

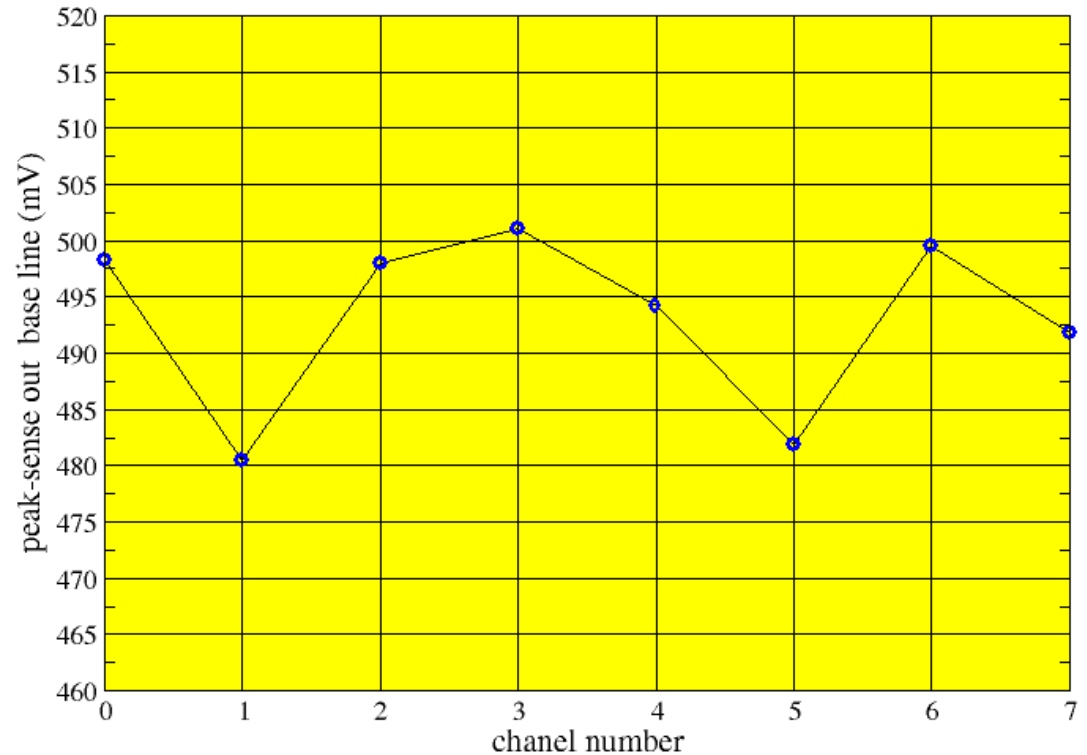


→ Variation of baseline vs. channel no. and vs. power supply:

Ch. no.	Power supply			Δ	
	3.0 V	3.3 V	3.6 V		
0	498.89	498.30	497.87	1.02	mV
1	480.75	480.41	480.25	0.50	
2	498.58	497.95	497.62	0.96	
3	501.82	501.13	500.74	1.08	
4	491.99	491.81	491.89	0.10	
5	499.92	499.51	499.34	0.58	
6	482.04	481.81	481.82	0.22	
7	494.52	494.24	494.09	0.43	

Peak sense out

Chip peak-sense out base line



GAIN and PULSE SHAPING FUNCTION

⇒ Conversion gain vs. channel no. and vs. shaping:

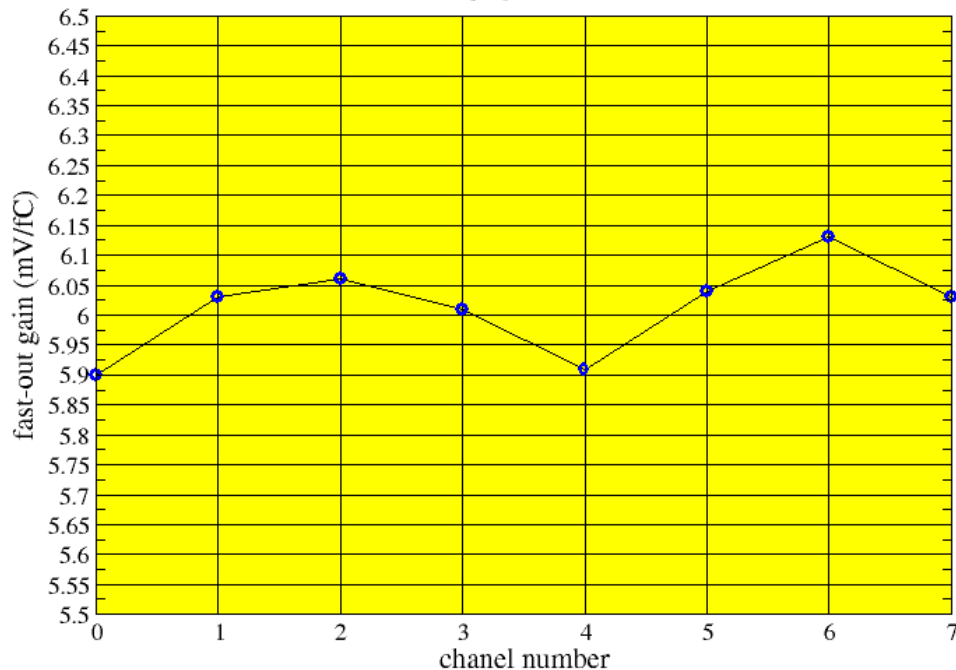
conversion gain = output voltage signal / input charge signal

$$Q_{inj} = 165 \text{ fC} \quad C_{inj} = 2.13 \text{ pF}, \quad C_{GND} \approx 10 \text{ pF}$$

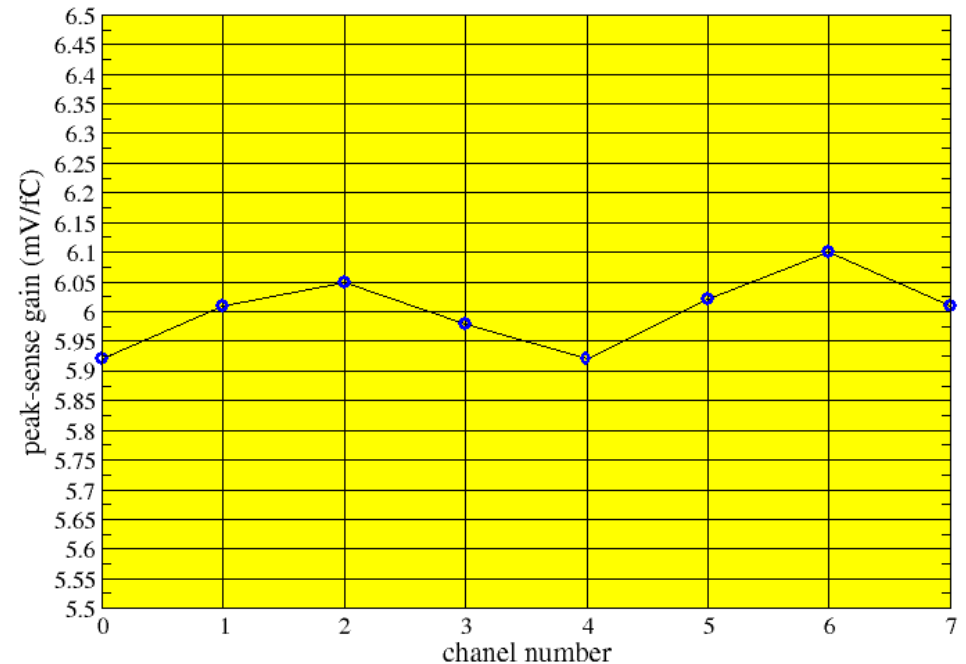
ch. no.	0	1	2	3	4	5	6	7	
Fast out	5,90	6,03	6,06	6,01	6,03	6,13	6,04	5,91	mV/fC
Peak sense out	5,92	6,01	6,05	5,98	6,01	6,10	6,02	5,92	

Predicted:
6.10 mV/fC

Chip fast-out gain
shaping time 40ns

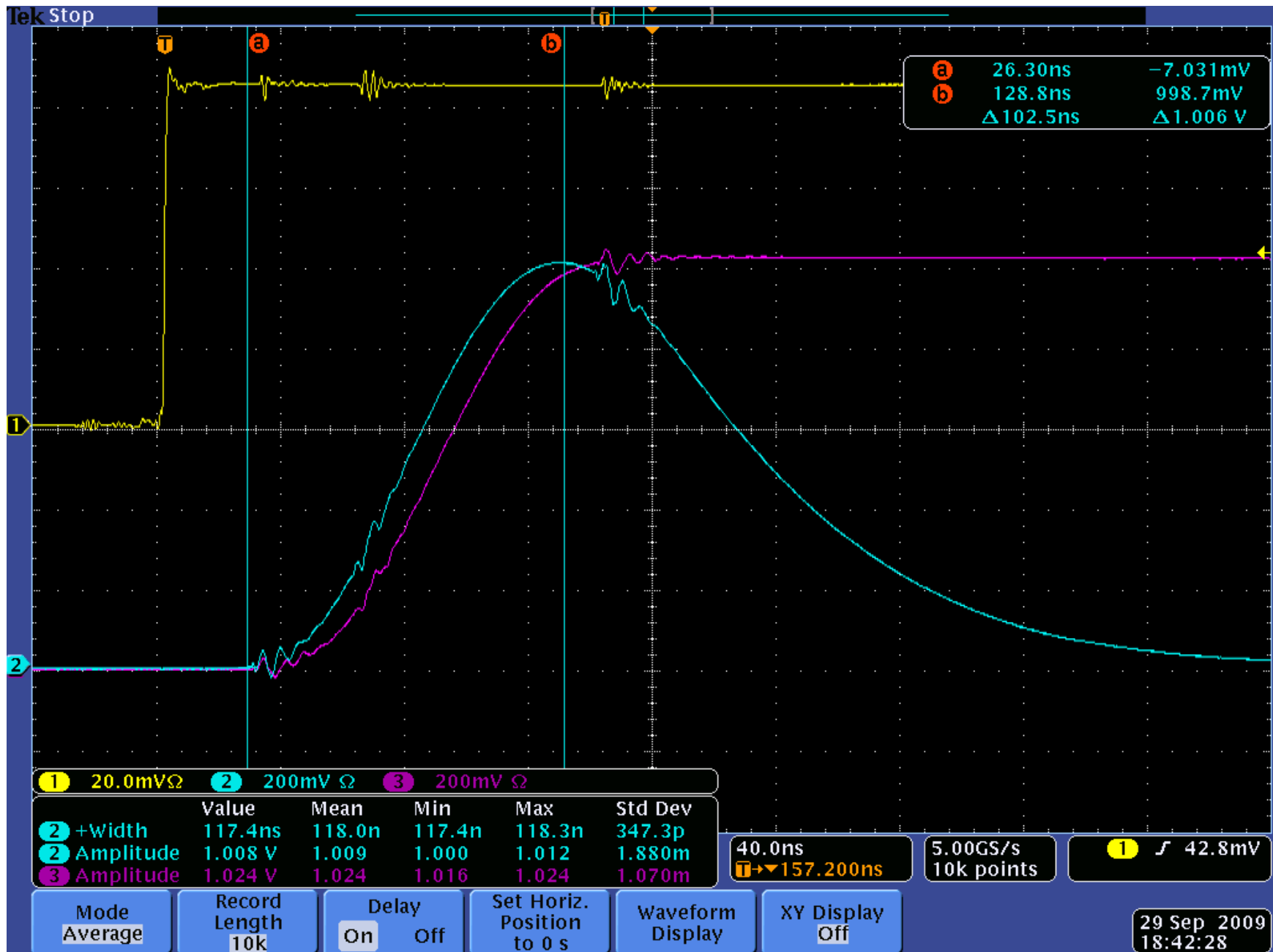


Chip peak-sense gain
shaping time 40ns

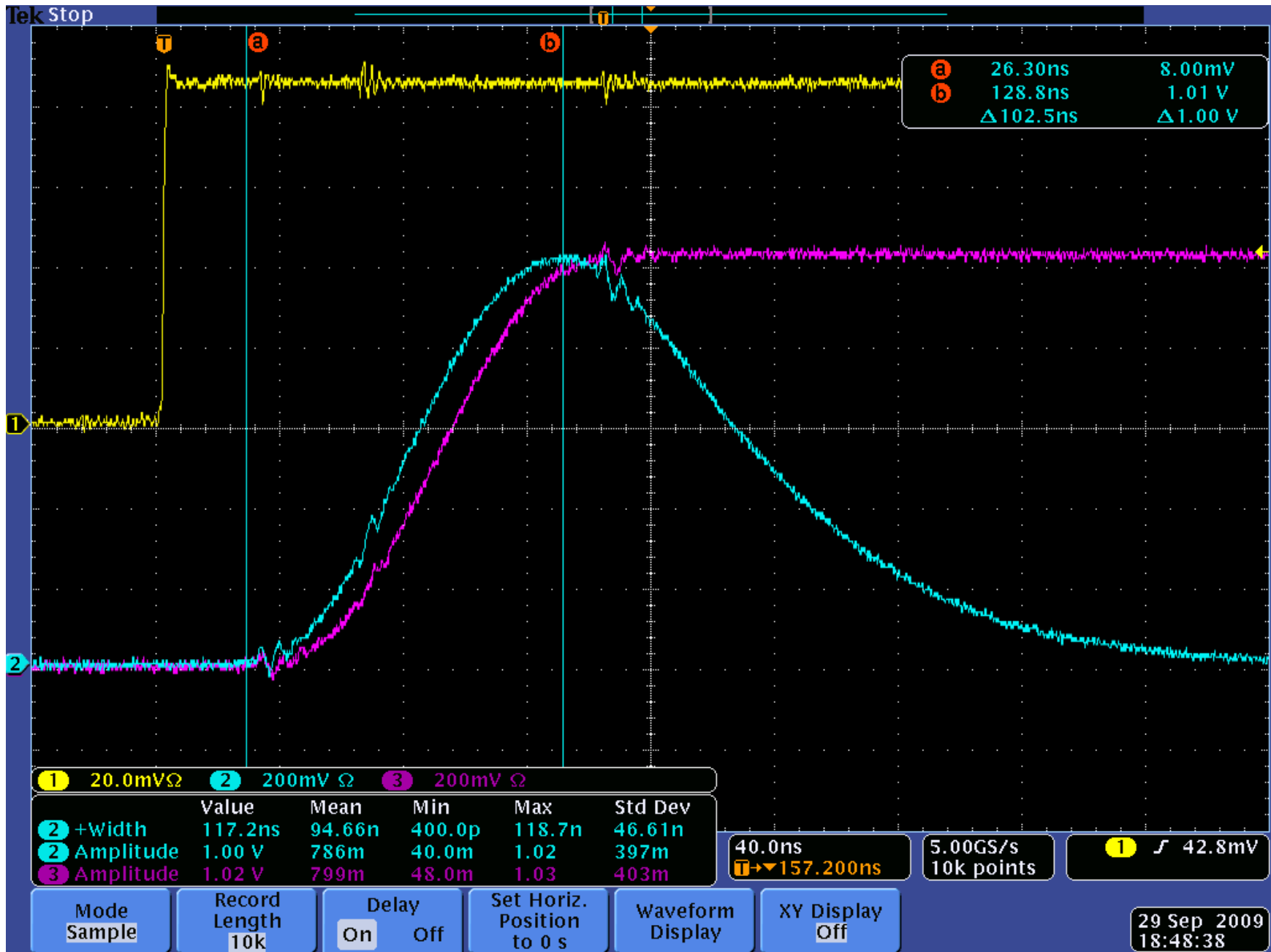


→ Pulse Shaping

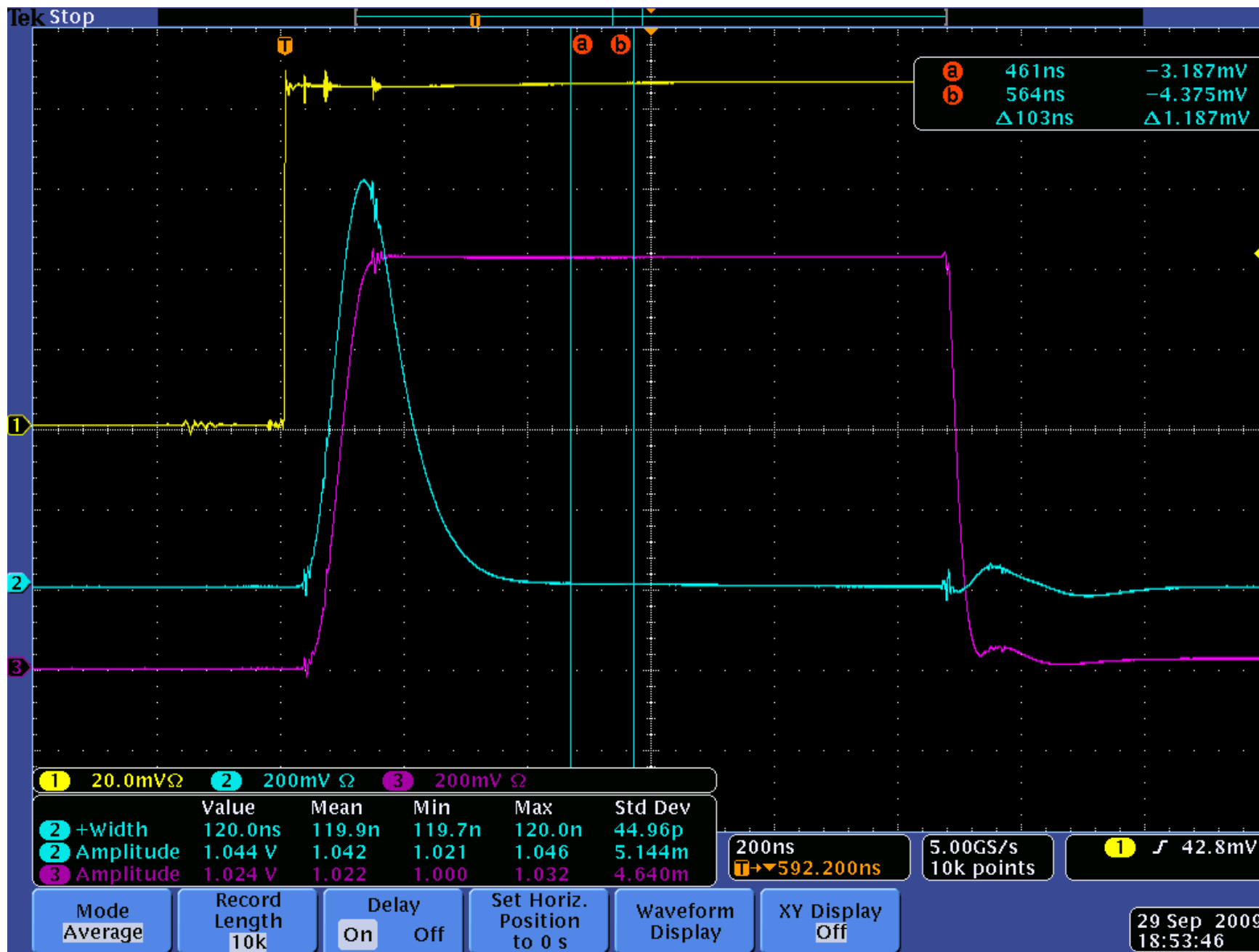
Fast out and peak sense out – details (avg.)



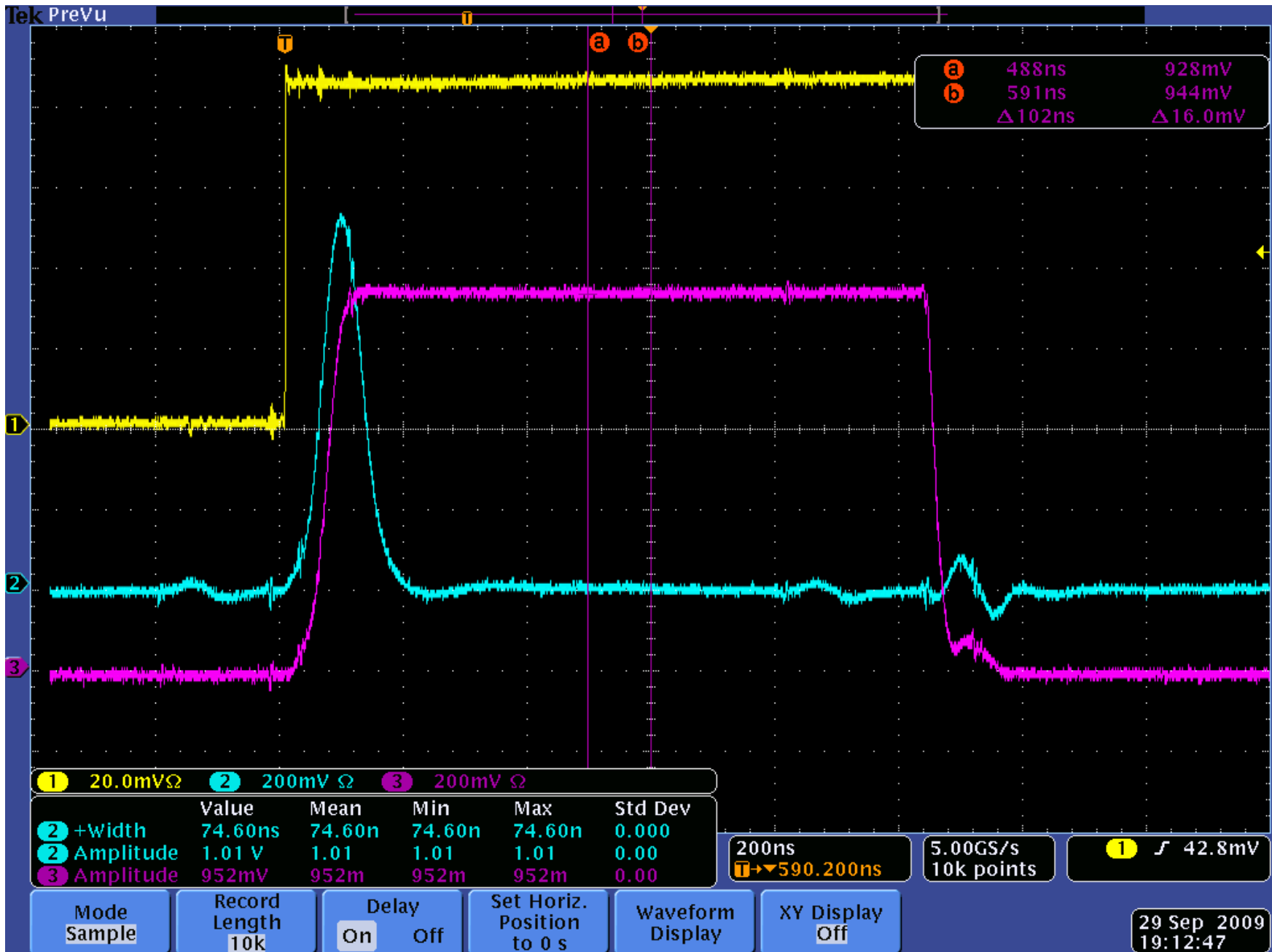
Fast out and peak sense out – details (with noise)



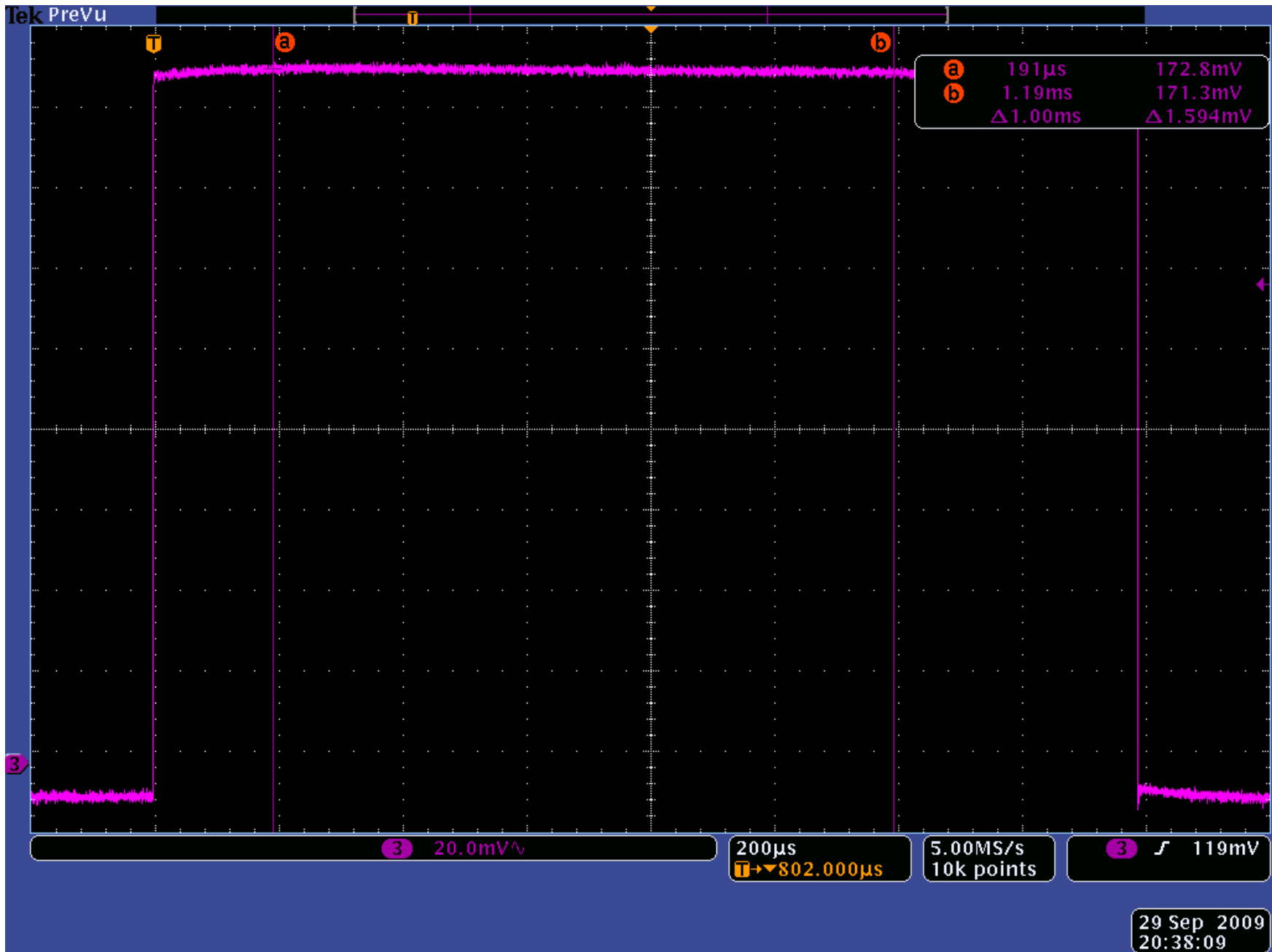
Fast out and peak sense out – complete shapes



Fast out and peak sense out – 20 ns shaping time



Peak sense out – decay slope

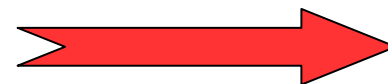


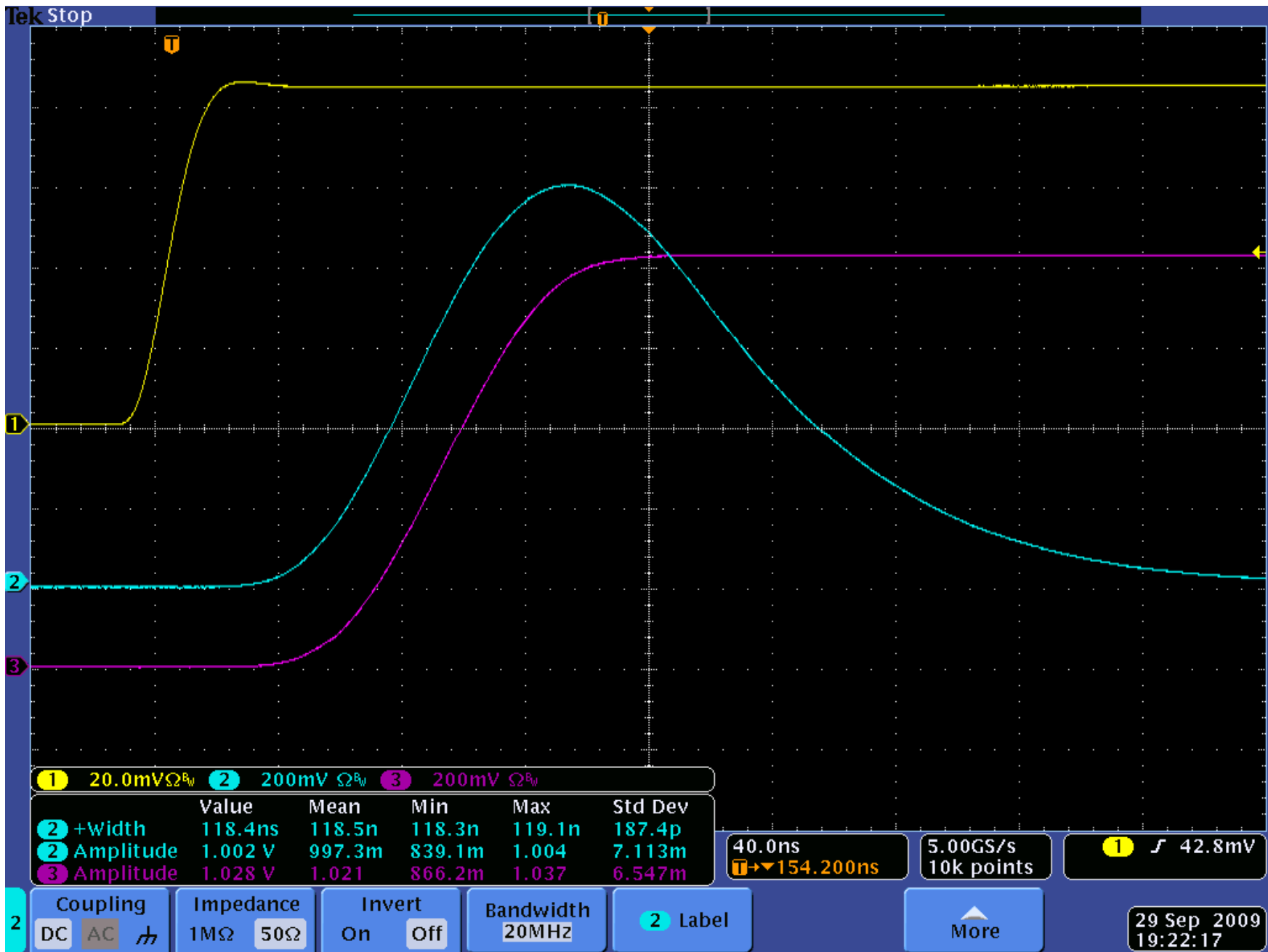
Summary:

- Spikes were observed at:
 - threshold level
 - peak detection
 - RDY command (peak sense pulse discharge)

→ grounding problems?
→ coupling problems?
(detailed tests will find their origin)
- Fast output:
 - FWHM time = 118 ns / 110 ns predicted value
 - time to peak = 102 ns
- Flat top:
 - decay $\approx 20 \mu\text{V}/\mu\text{s}$ / $25 \mu\text{V}/\mu\text{s}$ predicted

What we hope

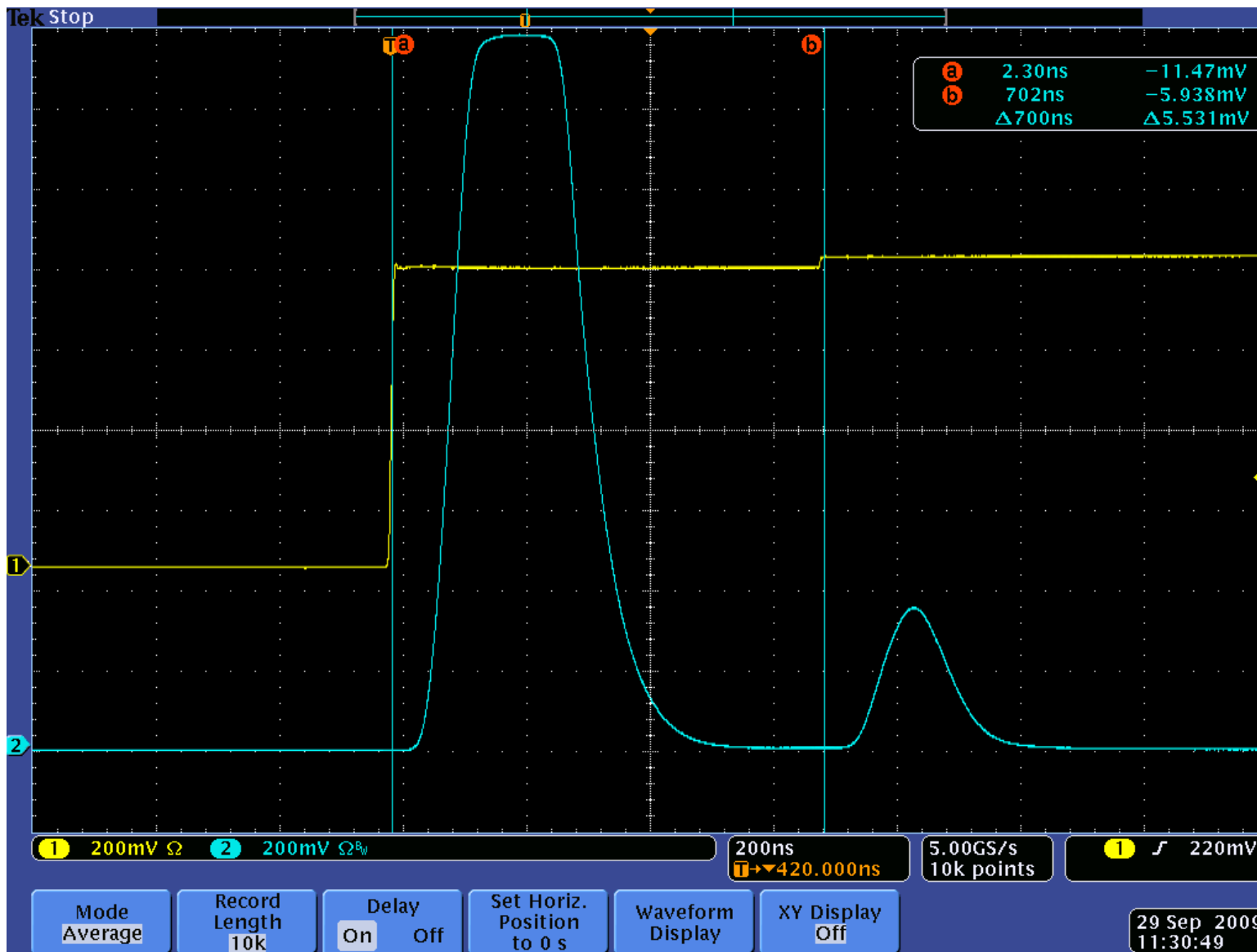




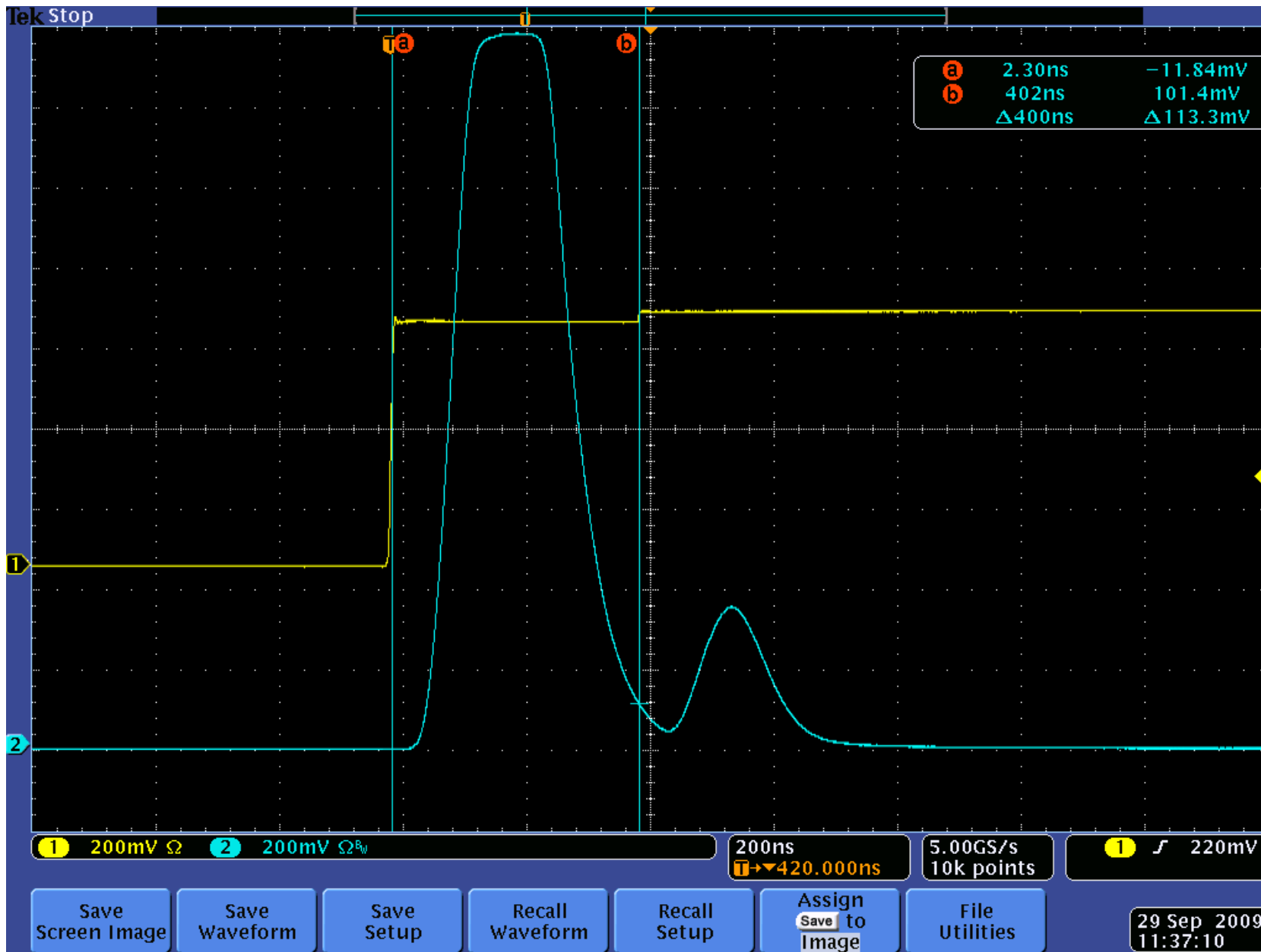
We hope to obtain above shapes ... for larger bandwidth than 20 MHz!

FAST OVERLOAD RECOVERY FUNCTION

- Purpose: to permit correct processing of a signal at shortest time after a strong overloaded pulse
- Level of overloading: x10 full amplitude range (1.65 pC)



700 ns
delay between
pulses



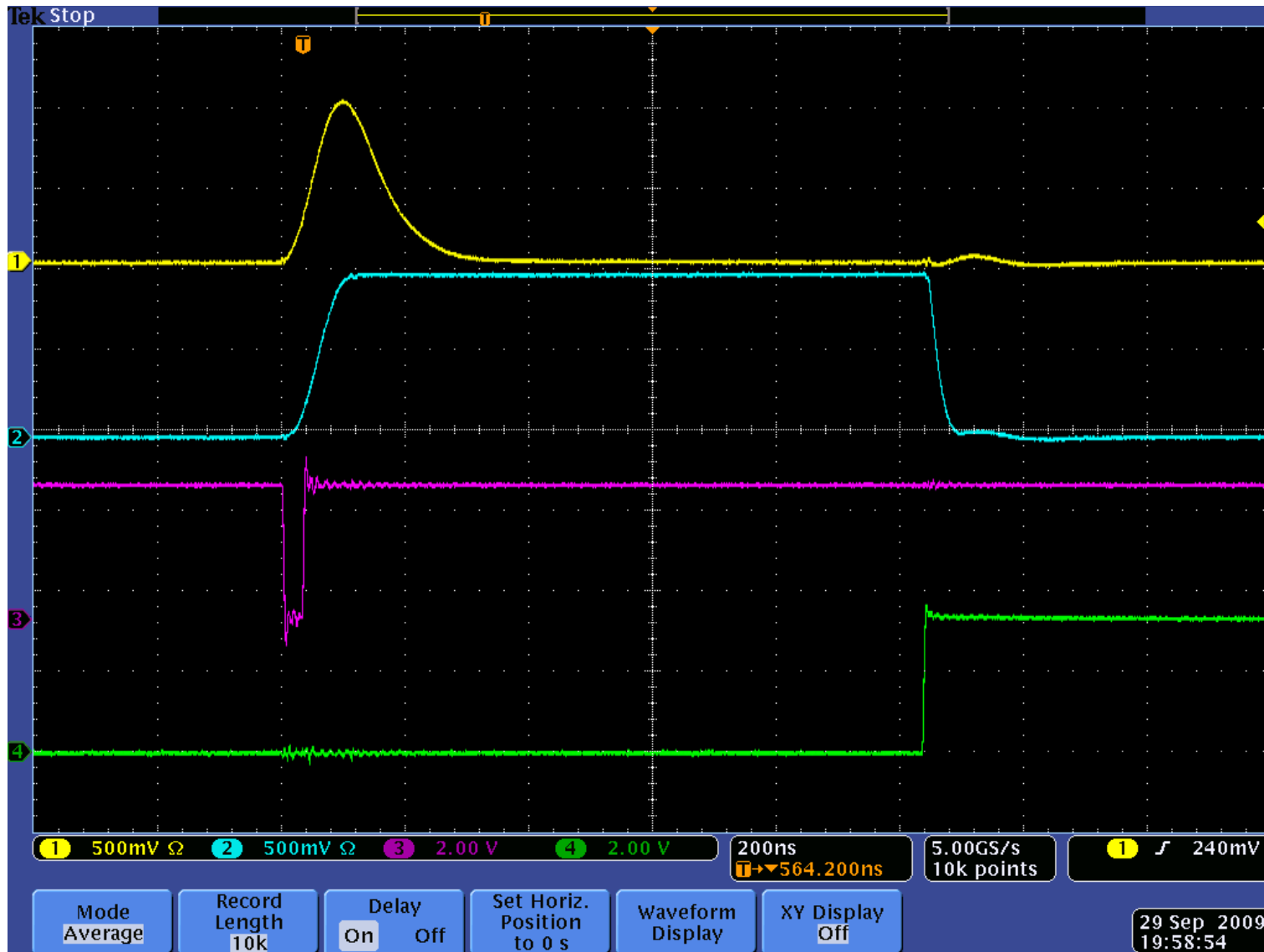
400 ns
delay
between
pulses

Excellent action of fast recovery circuitry!

Design specification: over 300 Kcps

LOGIC FUNCTION

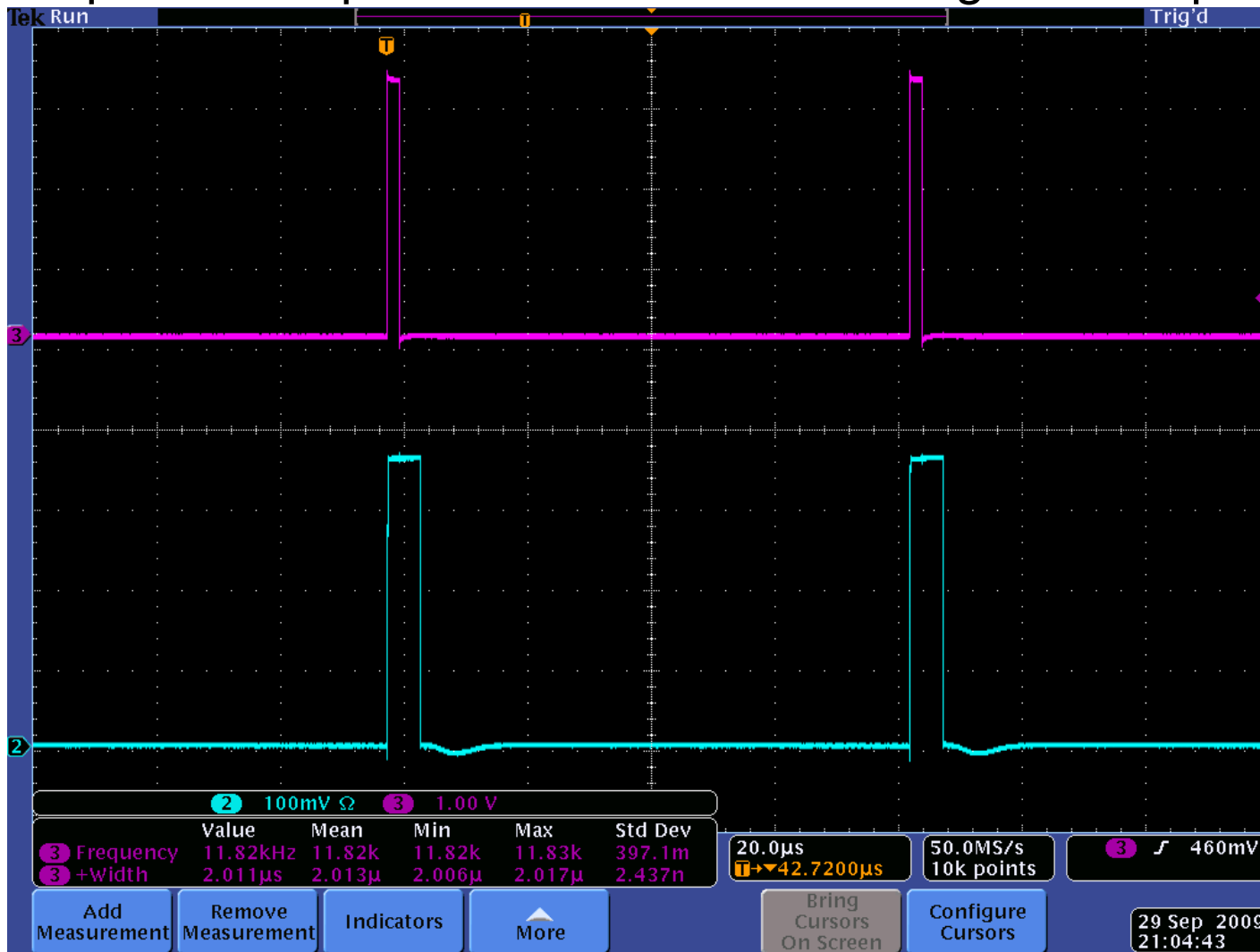
- Logic sequence:
 - EVT signal
 - RDY signal (the end of REQ signal)



TEST GENERATOR FUNCTION

- Function: to test the functionality of signal channels
- Controls: - external triggering (test board, mother board)
 - external reference for amplitude (test board, mother board)

Response of a peak sense channel to the generator pulses



NEXT STEPS

- The presented results were obtained only on one CHIP. 50 chips were produced (8 are bonded).
- Next steps
 - complete and accurate electronic tests
 - chip tests on HCR-TRD prototypes
 - diagnosis
 - an improved ASIC, test and mother boards
 - or
 - an improved version of the chip
 - if it will be necessary!

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